

# **UNIVERSITI PUTRA MALAYSIA**

DESIGN OF SILICON NITRIDE METAL-INSULATOR-METAL CAPACITOR USING 0.15 μm GALLIUM ARSENIDE TECHNOLOGY

**RASIDAH SANUSI** 

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## DESIGN OF SILICON NITRIDE METAL-INSULATOR-METAL CAPACITOR USING 0.15 µm GALLIUM ARSENIDE TECHNOLOGY



By

**RASIDAH SANUSI** 

Thesis Submitted to the School of Graduate Studies, Universiti Putra Malaysia, in Fulfilment of the Requirements for the Degree of Master of Science

October 2010

This work is dedicated to my beloved *parents* 

Hj. Sanusi Hassan

&

Hjh. Siti Ramlah Kosnan

And not forgotten to my *brothers* and *sisters* 

Hj. Dr. Sahrir Hj. Sanusi

Saidi Hj. Sanusi

Hj. Abdul Rahman Hj. Sanusi

Hasnah Hj. Sanusi

Soliha Hj. Sanusi

Solihaton Hj. Sanusi

Mohd Amin Hj. Sanusi

Mohd Hassan Hj. Sanusi

-Ci

Abstract of thesis presented to the Senate of Universiti Putra Malaysia in fulfilment of the requirement for the degree of Master of Science

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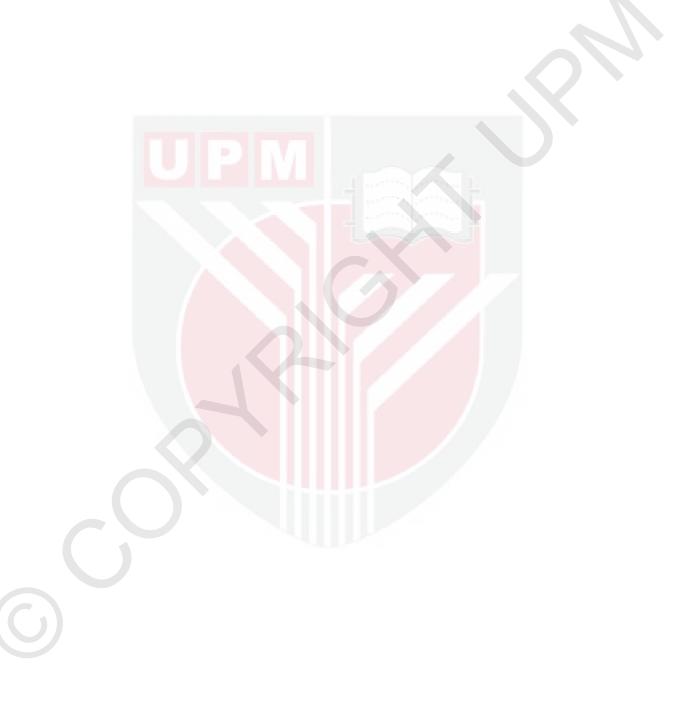
Chairperson : Associate Professor Roslina Mohd Sidek, PhD

Faculty

: Engineering

Generally there are two groups of devices in GaAs technology, which are active and passive devices. Passive devices commonly used in GaAs are resistor, capacitor, inductor and transmission lines. This research work only focus on MIM capacitor device.

The aim of this research work is to design and develop a model for  $Si_3N_4$  MIM capacitor type which are fabricated on GaAs substrate so that they could be used in high frequency, as an example 2.4 GHz frequency (S band) of applications. Physical and electrical characteristics of the  $Si_3N_4$  MIM capacitor devices for 0.15 µm GaAs technology are analyzed during layout design stage. 19 dimensions of  $Si_3N_4$  MIM capacitor layout design are sent for fabrication. The fabricated devices are measured at frequency range between 0.1 to 20 GHz, and their electrical performances show some variation when compared to the simulation. Due to the variation of the devices, an equivalent circuit which represents the electrical performance of measured devices is introduced. Through tuning and optimization, model parameters of the equivalent circuit which fit to the measurement value was obtained.



#### ACKNOWLEDGEMENTS

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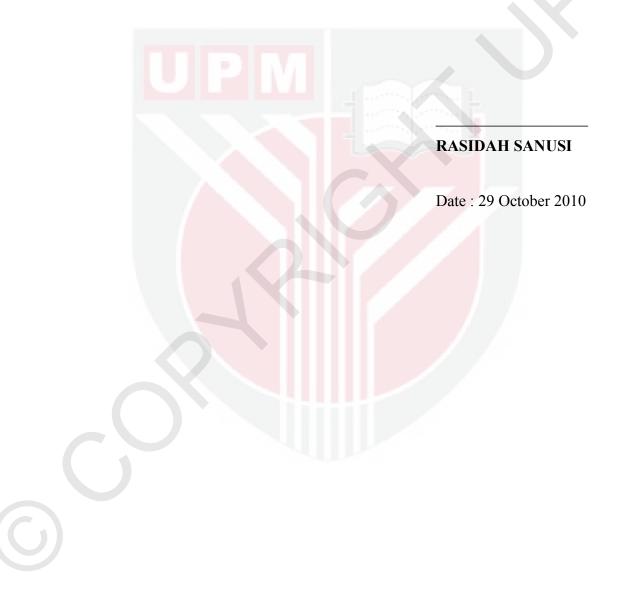
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Date :

## DECLARATION

I declare that the thesis is my original work except for quotations and citations which have been duly acknowledged. I also declare that it has not been previously, and is not concurrently submitted for any other degree at UPM or other institutions.



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